

ABSTRACT

WAFER POLISHING METHOD AND DOUBLE SIDE POLISHING APPARATUS

Provided is a wafer polishing method wherein the both surfaces of a wafer are simultaneously polished by sandwiching the wafer and sliding the wafer with a pressure by means of at least a lower plate, which is rotary-driven and has a flat polishing upper surface, an upper plate, which is arranged to face the lower plate, is rotary-driven and has a flat polishing lower surface, and a carrier having a wafer holding hole for holding the wafer. The wafer is polished while having the thickness thereof measured from a plurality of holes arranged between the rotating center and the periphery of the upper plate or the lower plate, and a polishing slurry is switched to that of a different polishing speed while the wafer is being polished. Thus, the wafer having high planarity and high smoothness is manufactured with high productivity and high yield.

Figure: 7